

HEWLETT  PACKARD

OPERATING AND SERVICE MANUAL

12597A-005

TAPE PUNCH INTERFACE KIT

(FOR 2100 SERIES COMPUTERS)

Card Assembly
12597-6001, Rev 832



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TABLE OF CONTENTS

Section	Page	Section	Page
I GENERAL INFORMATION		IV THEORY OF OPERATION	
1-1. Introduction	1-1	4-1. Introduction	4-1
1-3. Description	1-1	4-3. Functional Theory of Operation	4-1
1-4. General	1-1	4-11. Detailed Theory of Operation	4-1
1-6. Interface Kit Contents	1-1	4-12. General	4-1
1-8. Specifications	1-1	4-17. Power-On Logic	4-1
1-10. Identification	1-2	4-20. Input Register Logic	4-3
II INSTALLATION		4-23. Flag Logic	4-3
2-1. Introduction	2-1	4-29. Skip-On-Flag Signal	4-3
2-3. Unpacking and Inspection	2-1	4-30. Interrupt Signals	4-4
2-5. Reshipment	2-1	4-34. Service Request Signal	4-4
2-9. Preparation for Installation	2-1	4-36. Output Register Logic	4-7
2-10. Current Requirements	2-1	4-38. Command Logic	4-7
2-12. Interface Card Jumpers	2-1		
2-14. Installation	2-1		
III PROGRAMMING		V MAINTENANCE	
3-1. Introduction	3-1	5-1. Introduction	5-1
3-3. General Information	3-1	5-3. Preventive Maintenance	5-1
3-5. I/O Addressing	3-1	5-6. Troubleshooting	5-1
3-7. Sample Program	3-1		
		VI REPLACEABLE PARTS	
		6-1. Introduction	6-1
		6-5. Ordering Information	6-1

LIST OF ILLUSTRATIONS

Figure	Title	Page	Figure	Title	Page
1-1.	HP 12597A-005 Tape Punch Interface Kit . .	1-1	4-4.	Overall Timing Diagram Showing Operation with 2114, 2115, and 2116 Computers . .	4-5
2-1.	Power Lamp Wiring Diagram	2-2	4-5.	Overall Timing Diagram Showing Operation with 2100 and 21MX Computers	4-6
4-1.	Tape Punch Interface Card Functional Operation Flow Chart	4-2	5-1.	Integrated Circuit Pin Connections and Characteristics	5-2
4-2.	Skip-On-Flag Signal Generation Flow Chart . .	4-3	5-2.	Tape Punch Interface Card Parts Location Diagram and Logic Diagram	5-3
4-3.	Interrupt Operation Flow Chart	4-4			

LIST OF TABLES

Table	Title	Page	Table	Title	Page
1-1.	Tape Punch Interface Kit Specifications . . .	1-1	5-2.	Interface Cable Signal Index	5-2
2-1.	Interface Card Jumper Positions	2-1	6-1.	Numerical Listing of Replaceable Parts	6-2
3-1.	Sample Program	3-2	6-2.	Reference Designations and Abbreviations . .	6-3
5-1.	Tape Punch Interface Card Replaceable Parts List	5-1	6-3.	Code List of Manufacturers	6-4

SECTION I

GENERAL INFORMATION

1-1. INTRODUCTION.

1-2. This manual provides general information, installation instructions, programming instructions, theory of operation, maintenance information, and replaceable parts information for the Hewlett-Packard (HP) 12597A-005 Tape Punch Interface Kit (see figure 1-1).

1-3. DESCRIPTION.

1-4. GENERAL.

1-5. The HP 12597A-005 Tape Punch Interface Kit is an option to the standard HP 12597A 8-Bit Duplex Register Interface Kit. This kit supplies the interfacing requirements for the addition of an HP 2895A or HP 2895B Tape Punch to the user's computer system.

1-6. INTERFACE KIT CONTENTS.

1-7. The HP 12597A-005 Tape Punch Interface Kit consists of the following:

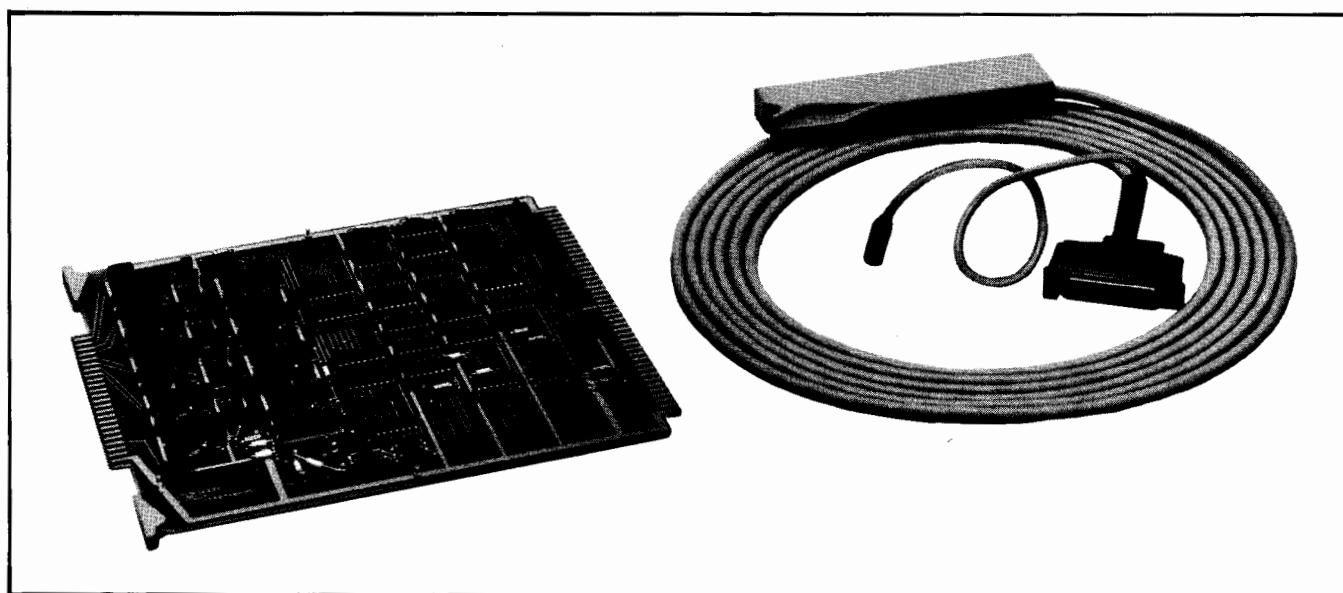
- a. Tape Punch Interface card (part no. 12597-6001).
- b. Interface cable (part no. 12597-60061).
- c. Test connector, 24-pin (part no. 1251-0332).
- d. Operating and service manual (part no. 12597-90025).

1-8. SPECIFICATIONS.

1-9. Table 1-1 lists the specifications for the HP 12597A-005 Tape Punch Interface Kit.

Table 1-1. Tape Punch Interface Kit Specifications

CHARACTERISTICS	SPECIFICATIONS
Output Levels: "1" state "0" state	0 to +0.5V, 12 mA sink maximum +12V, 10K source
Input Levels: "1" state "0" state	0 to +0.5V, 12 mA sink maximum +8V
Computer Power Supply Current Requirements: +12V -12V -2V +4.5V	0.05A 0.02A 0.05A 0.75A
Interface Card Dimensions: Width Height	7-3/4 inches (196.8 mm) 8-11/16 inches (220.7 mm)
Interface Kit Weight: Net Weight Shipping Weight	18 oz (675 gm) 4 lb (1.8 kg)



2158-1

Figure 1-1. HP 12597A-005 Tape Punch Interface Kit -

1-10. IDENTIFICATION.

1-11. This operating and service manual is identified on the title page by interface kit designation and nomenclature, card assembly part number and revision code, manual part number, and publication date. Refer to the information presented in the following paragraphs and ensure that this manual applies to the equipment being serviced.

1-12. Hewlett-Packard uses five digits and a letter (00000A) for standard interface kit designations and a 3-digit suffix (-000) for options to standard interface kits. If the designation of your kit does not agree with that on the title page of this manual, there are differences between your kit and the kit described in this manual. The appropriate manual or manual supplement is available at the

nearest HP Sales and Service Office listed at the back of this manual.

1-13. Printed-circuit cards used as plug-in card assemblies or fixed wired assemblies are identified by a letter, a revision code, and a division code stamped on the card (e.g., A-832-6). The letter identifies the version of the etched trace pattern on the unloaded card. The revision code (three middle digits) refers to the electrical characteristics of the loaded card. The division code (last digit) identifies the Hewlett-Packard division which manufactured the card. If the revision code on the printed-circuit card does not agree with the revision code shown on the title page of this manual, there are differences between your card and the card described in this manual. These differences are described in manual supplements available at the nearest HP Sales and Service Office.

SECTION II

INSTALLATION

2-1. INTRODUCTION.

2-2. This section provides information on unpacking and inspection, reshipment, preparation for installation, and installation of the tape punch interface kit.

2-3. UNPACKING AND INSPECTION.

2-4. If the shipping carton is damaged upon receipt, request that the carrier's agent be present when the kit contents are unpacked. Inspect the card for damage (cracks, broken parts, etc.). If the card is damaged and fails to meet specifications, notify the carrier and the nearest HP Sales and Service Office immediately. (Sales and Service Offices are listed at the back of this manual.) Retain the shipping container and packing material for the carrier's inspection. The HP Sales and Service Office will arrange for repair or replacement of the damaged card without waiting for any claims against the carrier to be settled.

2-5. RESHIPMENT.

2-6. If an item of the kit is to be shipped to Hewlett-Packard for service or repair, attach a tag to the item identifying the owner and indicating the service or repair to be accomplished. Include the model number of the kit.

2-7. Pack the item in the original factory packing material if available. If the original material is not available, standard factory packing material can be obtained from the nearest Hewlett-Packard Sales and Service Office.

2-8. If standard factory packing material is not used, wrap the item in Air Cap TH-240 cushioning (manufactured by Sealed Air Corporation, Hawthorne, New Jersey), or equivalent, and place in a corrugated carton (200 pound test material). Seal the shipping carton securely and mark it "FRAGILE" to ensure careful handling.

2-9. PREPARATION FOR INSTALLATION.

2-10. CURRENT REQUIREMENTS.

2-11. The interface card in this kit obtains its operating current from the computer power supply. Before installing this interface card, determine the current requirements of this card in combination with all other interface or accessory cards already installed in the computer. The computer system documentation describes the procedure for calculating the total current requirements and lists the currents

available from the computer. If the total current requirements exceed the limitations of the computer power supply, a Hewlett-Packard power supply extender unit or I/O extender unit must be used. See table 1-1 for the current requirements of the tape punch interface card.

2-12. INTERFACE CARD JUMPERS.

2-13. There are several jumper wires on the tape punch interface card. These jumpers are used to adapt the card for use with I/O devices other than the tape punch. Before installing the interface card, ensure that the jumpers are positioned as described in table 2-1 (see figure 5-2 for physical location of the jumpers).

Table 2-1. Interface Card Jumper Positions

JUMPER	POSITION
W1	A
W2	A
W3	Connected
W4	Connected
W5	Connected
W6	Connected
W7	Connected
W8	Disconnected
W9	Disconnected

2-14. INSTALLATION.

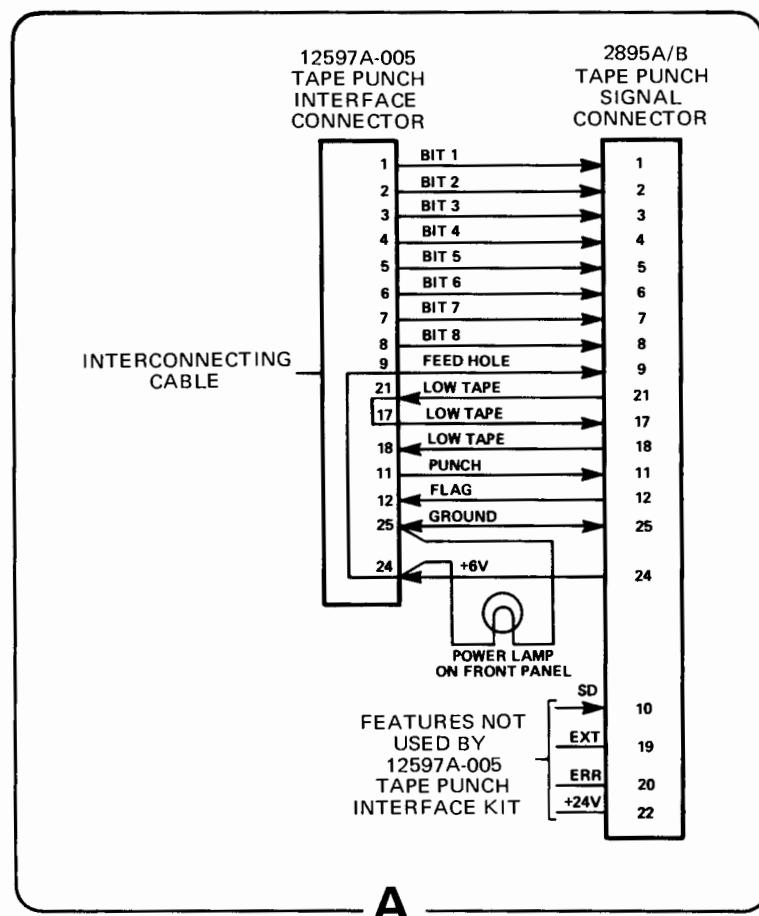
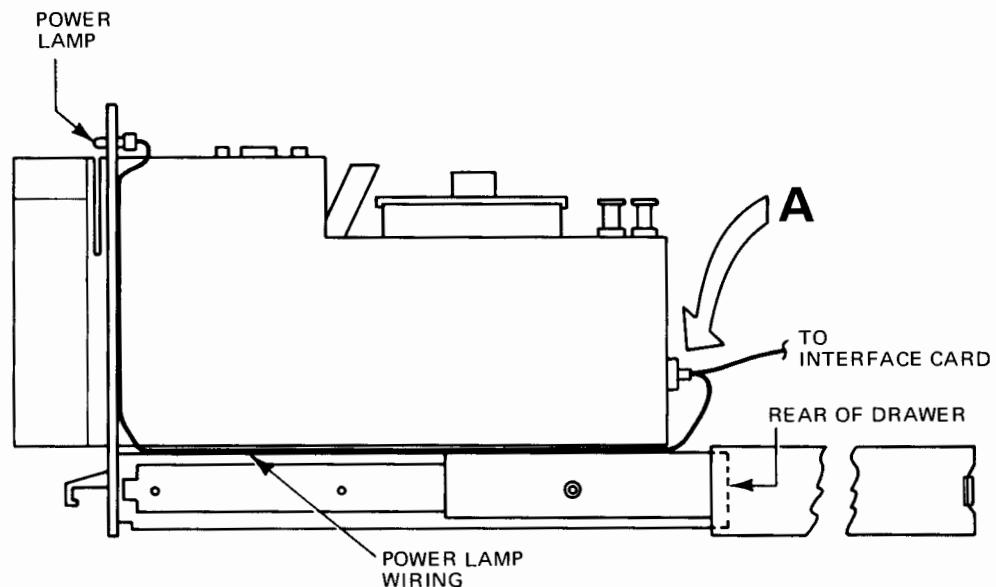
2-15. To install the tape punch interface kit, proceed as follows:

a. Turn off power at the computer and the tape punch.

b. Insert the interface card in the computer I/O card slot corresponding to the desired select code (address).

c. Connect the interconnecting cable between the interface card and the tape punch. Then connect the POWER lamp wiring portion of interconnecting cable to the POWER lamp on the front panel of the tape punch drawer. (See figure 2-1.)

d. Perform the diagnostic test described in the *High Speed Tape Reader/Punch Diagnostic Reference Manual*, part no. 12597-90031, to verify proper operation of the interface card and tape punch.



SECTION III

PROGRAMMING

3-1. INTRODUCTION.

3-2. This section provides programming information for the HP 12597A-005 Tape Punch Interface Kit.

3-3. GENERAL INFORMATION.

3-4. The tape punch interface card provides command logic to start the tape punch and flag logic to signal the computer when the tape punch has completed a punch operation. An output storage register provides buffer storage for transfer of eight bits of data from the computer to the tape punch, and an input storage register provides buffer storage for transfer of status information from the tape punch to the computer. The following paragraphs provide information required to program the operation of the command, flag, input register, and output register logic on the tape punch interface card.

3-5. I/O ADDRESSING.

3-6. Through the use of the I/O extender options, some HP computers are capable of operating up to 56 I/O devices. To provide orderly I/O operations, each I/O card slot is assigned a 2-digit octal address called a select code.

All program instructions calling for action by the tape punch interface card must include the select code of the interface card.

3-7. SAMPLE PROGRAM.

3-8. Table 3-1 provides a sample program showing the use of the tape punch interface card to operate an HP 2895A/B Tape Punch. The sample is an actual program listing prepared on an HP computer system using the HP Assembler software package.

3-9. Under control of the sample program, the tape punch will punch 100 8-bit data words as read from 100 consecutive memory locations. Prior to each data word transfer, the tape punch status will be checked for a possible low-tape condition. Low-tape is indicated by a logic 1 in bit 5 of the tape punch status word. To supply the I/O addressing requirements, the tape punch has been arbitrarily assigned a select code of 16 octal.

3-10. The sample program does not use the computer interrupt system. If the interrupt system has been previously enabled, a CLF 00 instruction must be included at the start of the program to turn off the interrupt system.



Table 3-1. Sample Program

```

0001          ASMB,A,B,L,T
0002*
0003* THIS IS A SAMPLE PROGRAM DEMONSTRATING THE OPERATION OF THE
0004* HP 12597A-005 TAPE PUNCH INTERFACE. UNDER CONTROL OF THIS
0005* PROGRAM, THE TAPE PUNCH WILL PUNCH 100, 8-BIT CHARACTERS AS READ
0006* FROM 100 CONSECUTIVE MEMORY LOCATIONS. THE TAPE PUNCH STATUS
0007* WILL BE CHECKED PRIOR TO EACH OUTPUT OPERATION AND AN HLT 66B
0008* DISPLAYED IF THE STATUS WORD INDICATES TAPE SUPPLY IS LOW.
0009*
0010 00400          ORG 400B    ASSIGN PROGRAM STARTING LOCATION
0011*                 OF 400 OCTAL.
0012 00400 060432   START LDA CNT   INITIALIZE COUNT-TO-100 COUNTER
0013 00401 070430   STA CNTR    AND STORE IN LOCATION CNTR.
0014 00402 060433   LDA ITBL    GET STARTING ADDRESS OF DATA TO BE
0015 00403 070431   STA PNTR    PUNCHED AND STORE IN PNTR.
0016*
0017 00404 014417   CHECK JSB STAT JUMP TO SUBROUTINE THAT WILL GET
0018*                 STATUS WORD.
0019 00405 010434   AND MASK   REMOVE INSIGNIFICANT STATUS BITS.
0020 00406 050435   CPA LOW    IS TAPE SUPPLY LOW?
0021 00407 102066   HLT 66B    YES. HALT COMPUTER.
0022 00410 160431   LDA PNTR,I NO. GET CHARACTER TO BE PUNCHED.
0023*
0024 00411 014422   JSB PUNCH  JUMP TO SUBROUTINE THAT WILL PUNCH
0025*                 A CHARACTER.
0026 00412 034431   ISZ PNTR   MOVE POINTER TO NEXT CHARACTER.
0027 00413 034430   ISZ CNTR   INCREMENT COUNTER. 100 OPERATIONS?
0028 00414 024404   JMP CHECK  NO. CHECK STATUS AND PUNCH AGAIN.
0029 00415 102077   HLT 77B   YES. NORMAL END OF PROGRAM.
0030 00416 024400   JMP START  TO RERUN PROGRAM PUSH "RUN".
0031*
0032* ** SUBROUTINE ** THIS ROUTINE GETS STATUS WORD FROM PUNCH.
0033*
0034 00417 000000   STAT NOP
0035 00420 102516   LIA TPIF   PUT STATUS WORD IN A-REGISTER.
0036 00421 124417   JMP STAT,I RETURN TO PROGRAM WITH STATUS WORD.
0037*
0038* ** SUBROUTINE ** THIS ROUTINE PUNCHES CHARACTER.
0039*
0040 00422 000000   PUNCH NOP
0041 00423 102316   SFS TPIF   IS TAPE PUNCH READY?
0042 00424 024423   JMP #-1    NO. WAIT.
0043 00425 102616   OTA TPIF   YES. PUT CHARACTER IN INTERFACE
0044*                 REGISTER.
0045 00426 103716   STC TPIF,C START TAPE PUNCH.
0046 00427 124422   JMP PUNCH,I RETURN TO PROGRAM.
0047*
0048* CONSTANT AND STORAGE INFORMATION.
0049*
0050 00430 000000   CNTR BSS 1  RESERVE ONE LOCATION FOR COUNTER.
0051 00431 000000   PNTR BSS 1  RESERVE ONE LOCATION FOR POINTER.
0052 00432 177634   CNT DEC -100 INITIAL COUNT FOR COUNTER.
0053 00433 000122   ITBL OCT 122 STARTING LOCATION OF DATA BLOCK.
0054 00016          TPIF EQU 16B TAPE PUNCH INTERFACE HAS S.C. 16B.
0055 00434 000040   MASK OCT 40
0056 00435 000040   LOW OCT 40  SAMPLE "LOW TAPE" STATUS WORD.
0057*
0058          END START
** NO ERRORS*

```

SECTION IV

THEORY OF OPERATION

4-1. INTRODUCTION.

4-2. This section provides the theory of operation for the 12597-6001 Tape Punch Interface Card.

4-3. FUNCTIONAL THEORY OF OPERATION.

4-4. Figure 4-1 is a flow chart showing the functional theory of operation for the tape punch interface card. The programmed instructions shown in the shaded area of the flow chart are the same as those used in the subroutine portions of the sample program (table 3-1) in Section III of this manual.

4-5. The first programmed instruction (LIA) transfers the tape punch status word from the input storage register to the computer A-register. The status word consists of a single bit (bit 5) that becomes a logic 1 when the tape punch paper tape supply is low. The status word is then checked by software. The computer will normally be programmed to halt if a low-tape condition exists.

4-6. Assuming that the status word does not indicate low tape (bit 5 is logic 0), the next step is to test the state (set or clear) of the Flag FF. If the Flag FF is in the clear state, the punch is busy from some previously programmed punch operation. If the Flag FF is set, the punch is ready to accept data for a new punch operation. An SFS instruction tests the Flag FF. If the Flag FF is clear, the next instruction (JMP *-1) causes the computer to again execute the SFS instruction. This loop continues until the Flag FF is set. An SFS instruction when the Flag FF is set causes the computer to skip the JMP *-1 instruction and continue with the program.

4-7. The computer can also be signaled when the Flag FF is set via interrupt signals (FLG and IRQ) or a Service Request (SRQ) signal. These signals are discussed in detail in paragraphs 4-30 through 4-35.

4-8. The next programmed instruction (OTA) transfers the data word that is to be punched from the computer A-register to the output storage register on the interface card. The tape punch now has data available and requires only that it be commanded to punch the data on paper tape.

4-9. A combined Set Control and Clear Flag (STC xx,C) instruction sets the Control and Command FFs, and clears the Flag Buffer and Flag FFs. The Command FF provides a Punch signal which starts the operation of the tape punch. This completes the programmed instructions required for a punch operation. The computer is now free to perform other operations while the tape punch is completing its operation.

4-10. The tape punch provides a Flag signal when it completes the punch operation. As shown by figure 4-1, the Flag signal sets the Flag Buffer FF and clears the Command FF. At the next computer time T2, an ENF signal sets the Flag FF to indicate that the tape punch is again ready for a new punch operation.

4-11. DETAILED THEORY OF OPERATION.

4-12. GENERAL.

4-13. Diagrams that support the detailed theory of operation for the tape punch interface card include the timing diagram in this section (figure 4-4 or 4-5) and the interface card logic diagram (figure 5-2) in Section V of this manual.

4-14. For an index of signals at the 86-pin edge of the interface card, see Volume Three of the computer system documentation. For an index of signals at the 48-pin edge of the interface card, see table 5-2 in Section V of this manual.

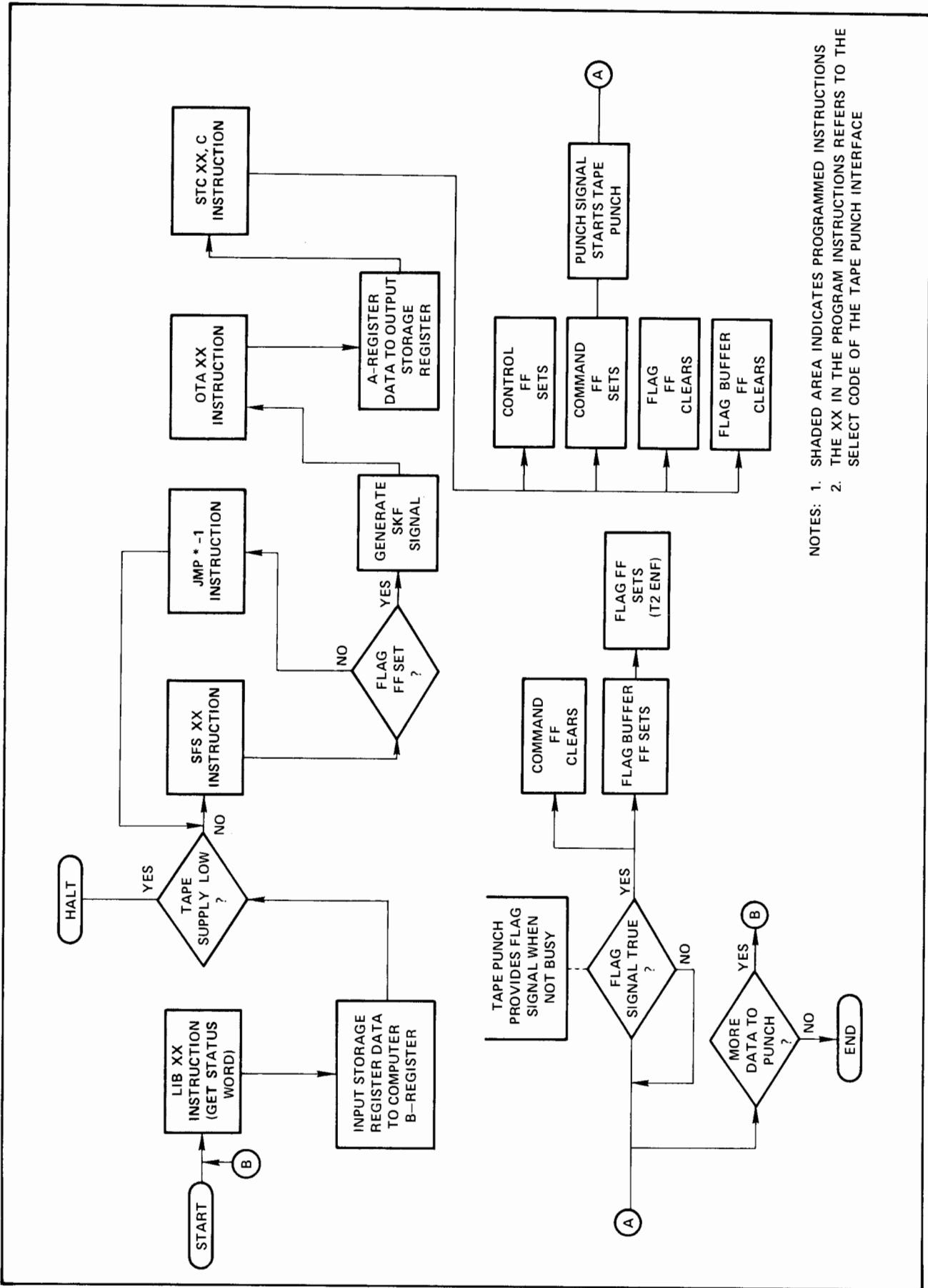
4-15. Logic levels between the computer and the interface card, and logic levels internal to the card are positive-true. The term "true" refers to a signal level of about +3.5 volts and "false" refers to a level of about ground. These signal levels vary somewhat depending on the integrated circuit package involved. Detailed signal level information for the various integrated circuit packages is provided in figure 5-1 in Section V of this manual.

4-16. Signal levels to and from the tape punch are ground-true and are detailed in table 1-1 in Section I of this manual.

4-17. POWER-ON LOGIC.

4-18. When power is initially applied to the computer or the computer PRESET switch is pressed, the computer supplies a POPIO and a CRS signal to the interface card. The POPIO signal sets the Flag Buffer FF and the CRS signal clears the Control and Command FFs. The Control FF, in the clear state, disables the interrupt circuitry on the interface card. A cleared Command FF ensures that the tape punch will be receiving a false Punch signal. At time T2, the computer generates an ENF signal which is gated with the set-side of the Flag Buffer FF to set the Flag FF. The ENF signal also ensures that the IRQ FF is in the clear state.

4-19. The initial operating conditions of the tape punch interface card after power-on are: Flag Buffer and Flag FFs set; Control, Command, and IRQ FFs cleared.



NOTES:

1. SHADED AREA INDICATES PROGRAMMED INSTRUCTIONS
2. THE XX IN THE PROGRAM INSTRUCTIONS REFERS TO THE SELECT CODE OF THE TAPE PUNCH INTERFACE

Figure 4-1. Tape Punch Interface Card Functional Operation Flow Chart

4-20. INPUT REGISTER LOGIC.

4-21. The input storage register on the tape punch interface card stores the tape punch status word. Although a full eight bits are transferred to the computer, the status word consists of a single significant bit (bit 5) and, as a logic 1, indicates that the paper tape supply is low. When the interface cable is connected, a ground is applied to pin 21 of the 48-pin edge of the card. This provides a continuous enable to the input storage register so that any change in the status bit is immediately loaded into the bit 5 flip-flop of the register.

4-22. A programmed LIA or LIB instruction addressed to the tape punch interface card provides true SCM, SCL, IOG, and IOI signals. The IOI signal strobes the status word onto the IOBI lines to the computer A- or B-register.

4-23. FLAG LOGIC.

4-24. Before transferring a data word from the computer to the tape punch, the computer must be assured that the punch is not busy operating from some previous data transfer. The state of the Flag FF (set or clear) provides this information to the computer. If the tape punch has not been previously operated, and the state of the Flag FF has not been altered by some programmed instruction, the Flag FF will be in the set state due to the action described in paragraph 4-18. If the tape punch is busy, the Flag FF will be in the clear state due to a programmed Clear Flag instruction described in paragraph 4-39.

4-25. At this point, the discussion of the flag logic assumes that the tape punch is busy and the Flag FF is in the clear state.

4-26. When the tape punch completes an operation, it provides a Flag signal to the interface card. The interface card converts the Flag signal to a 300 nanosecond pulse which clears the Command FF and sets the Flag Buffer FF.

4-27. The timing of the Flag logic at this point is dependent upon the timing of the tape punch and is not related to computer timing. An ENF signal, supplied by the computer every machine cycle at time T2, is gated with the output of the Flag Buffer FF (now in the set state) to set the Flag FF. This action synchronizes the effect of the Flag signal with the computer timing by allowing the Flag FF to be set only at computer time T2.

4-28. When the Flag FF is in the set state, the interface card flag logic responds by generating SKF, FLG and IRQ, or SRQ signals to indicate to the computer that the tape punch is ready to accept a data transfer. The following paragraphs describe how these signals are generated and how they affect computer operation.

4-29. SKIP-ON-FLAG SIGNAL. If the computer is programmed to wait for the Flag FF to be set (for example, an SFS instruction followed by a JMP *-1 instruction as shown in Figure 4-1), the resulting SFS signal gated with a true signal from the set side of the Flag FF generates an SKF signal. This causes the computer to skip the next instruction (in this case JMP *-1) and proceed with the program. Figure 4-2 illustrates the generation of an SKF signal by the interface card. Notice that an SKF signal can also be generated when the Flag FF is in the clear state by programming an SFC instruction. Either way, the state of the Flag FF is being tested and the computer must be programmed to respond accordingly.

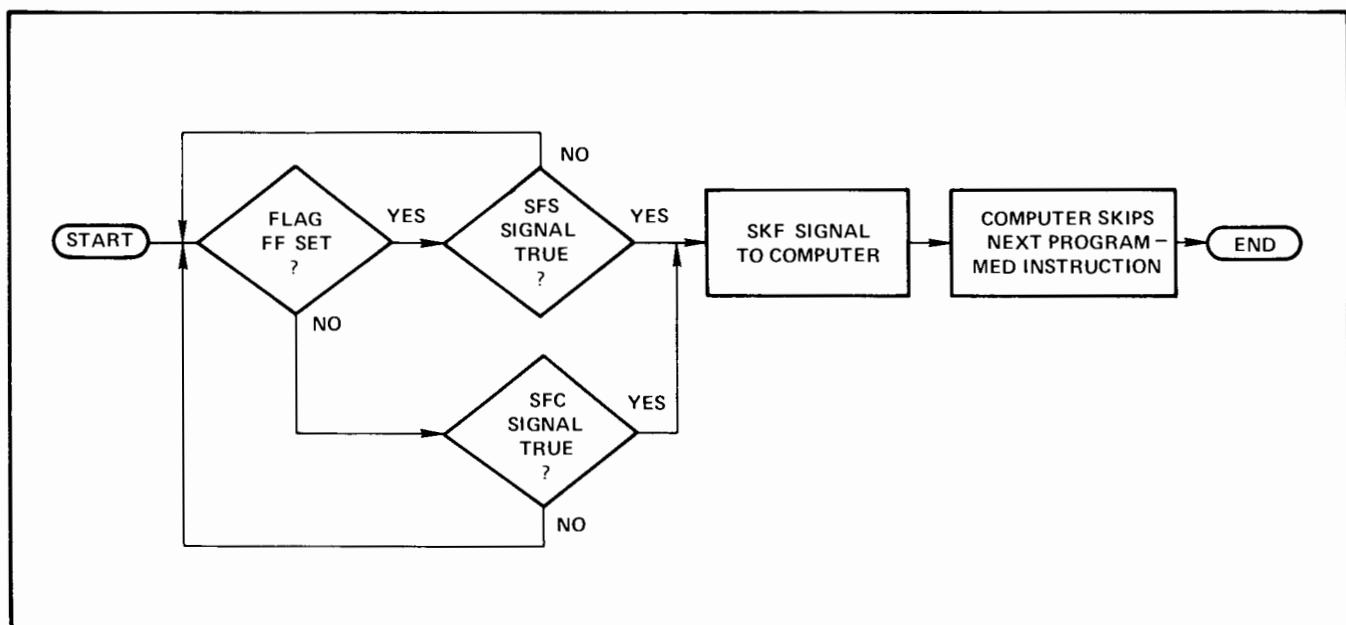


Figure 4-2. Skip-On-Flag Signal Generation Flow Chart

4-30. INTERRUPT SIGNALS. If the computer interrupt system has been enabled by an STF 00 instruction, the computer can be doing work in the main program rather than waiting for the Flag FF to be set. Figure 4-3 illustrates the functions involved in an interrupt operation. To interrupt the main program when the tape punch is ready, the following conditions must be met:

- Control FF set (paragraph 4-39).
- Flag Buffer FF set (paragraph 4-26).
- Flag FF set (paragraph 4-27).
- IEN signal true (interrupt system enabled).
- PRH signal true (no higher priority interrupts).

4-31. When all of these conditions are established, an SIR signal from the computer at time T5 sets the IRQ FF which generates true FLG and IRQ signals. These signals are used by the computer I/O control and addressing circuits to generate an interrupt request signal.

4-32. At time T2 after interrupt is initiated, an ENF signal clears the IRQ FF. An SIR signal again sets the IRQ FF at time T5 if the PRH signal is still true. The FLG and IRQ signals this time are used by the computer I/O control and addressing circuits to encode the interrupt address.

4-33. The next machine cycle is controlled by the instruction located at the interrupt address in memory. During this machine cycle, an IAK signal clears the Flag Buffer FF and an ENF signal at time T2 clears the IRQ FF. The Flag FF remains set to inhibit lower priority interrupts by providing a false PRL signal. A CLF instruction must be programmed to clear the Flag FF and enable lower priority interrupts just before returning to the main program.

4-34. SERVICE REQUEST SIGNAL. If the computer is equipped with the Direct Memory Access (DMA) option, and if the DMA circuits have been initialized, an 8-bit word can be transferred directly from memory to the tape punch

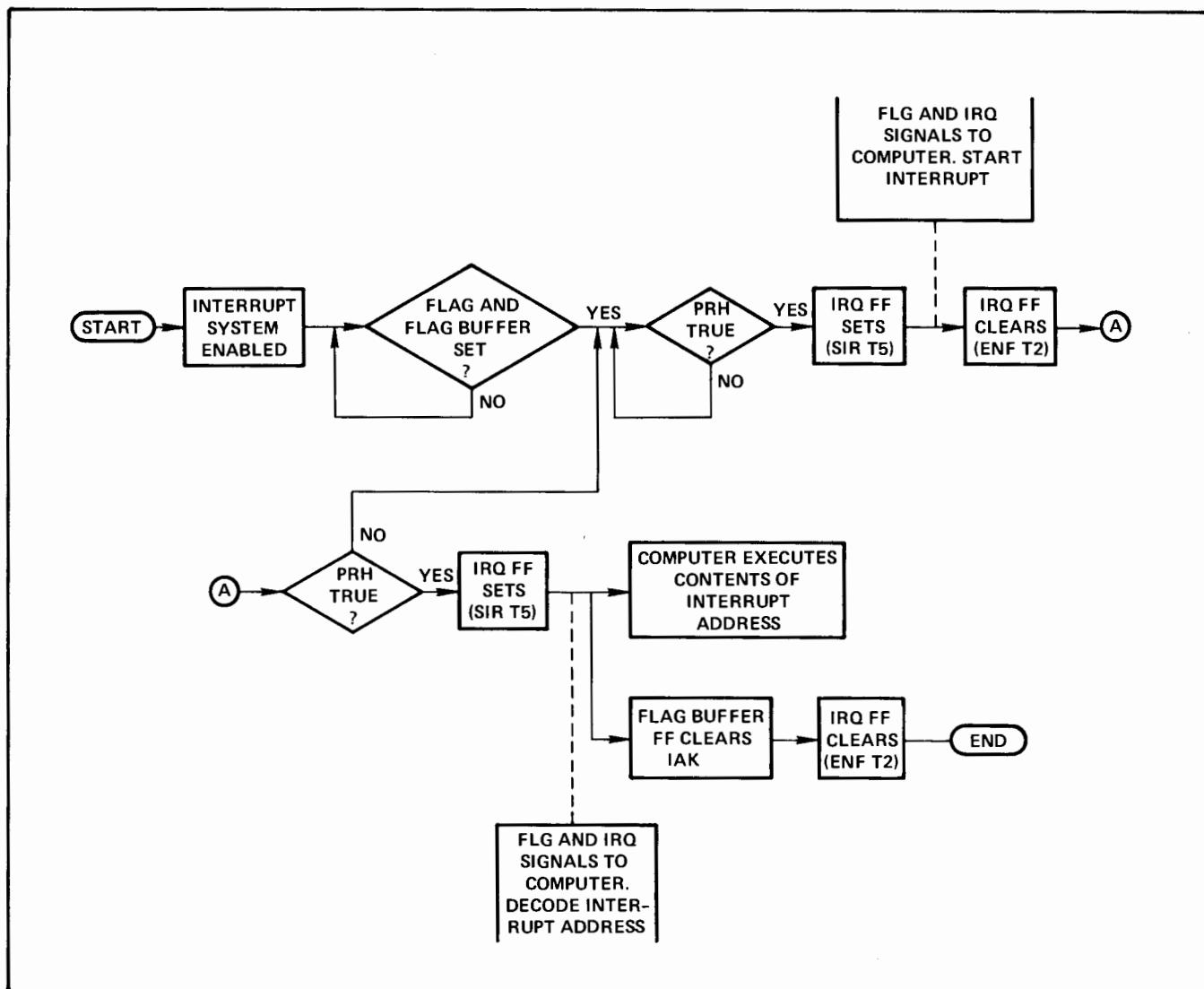
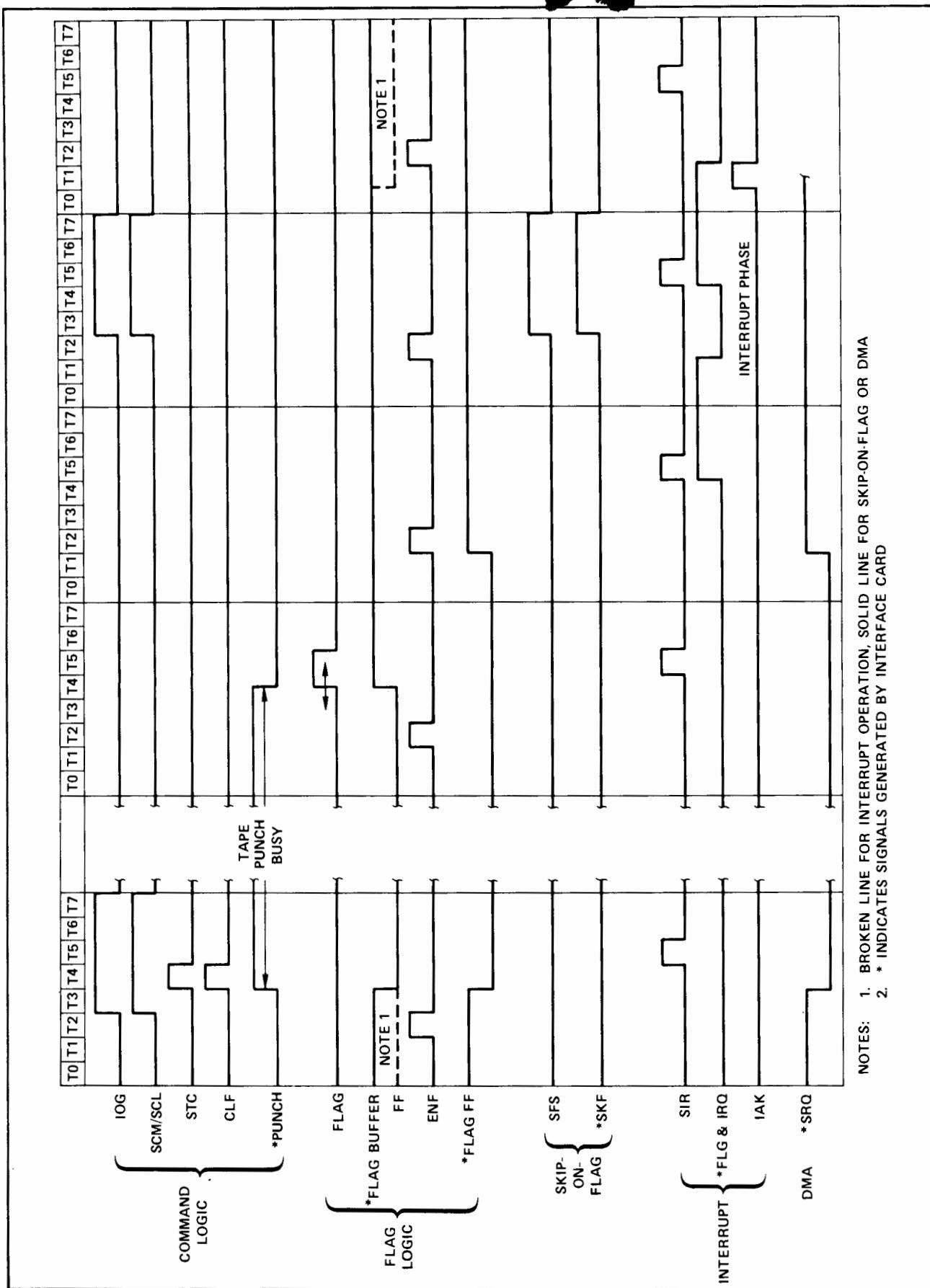
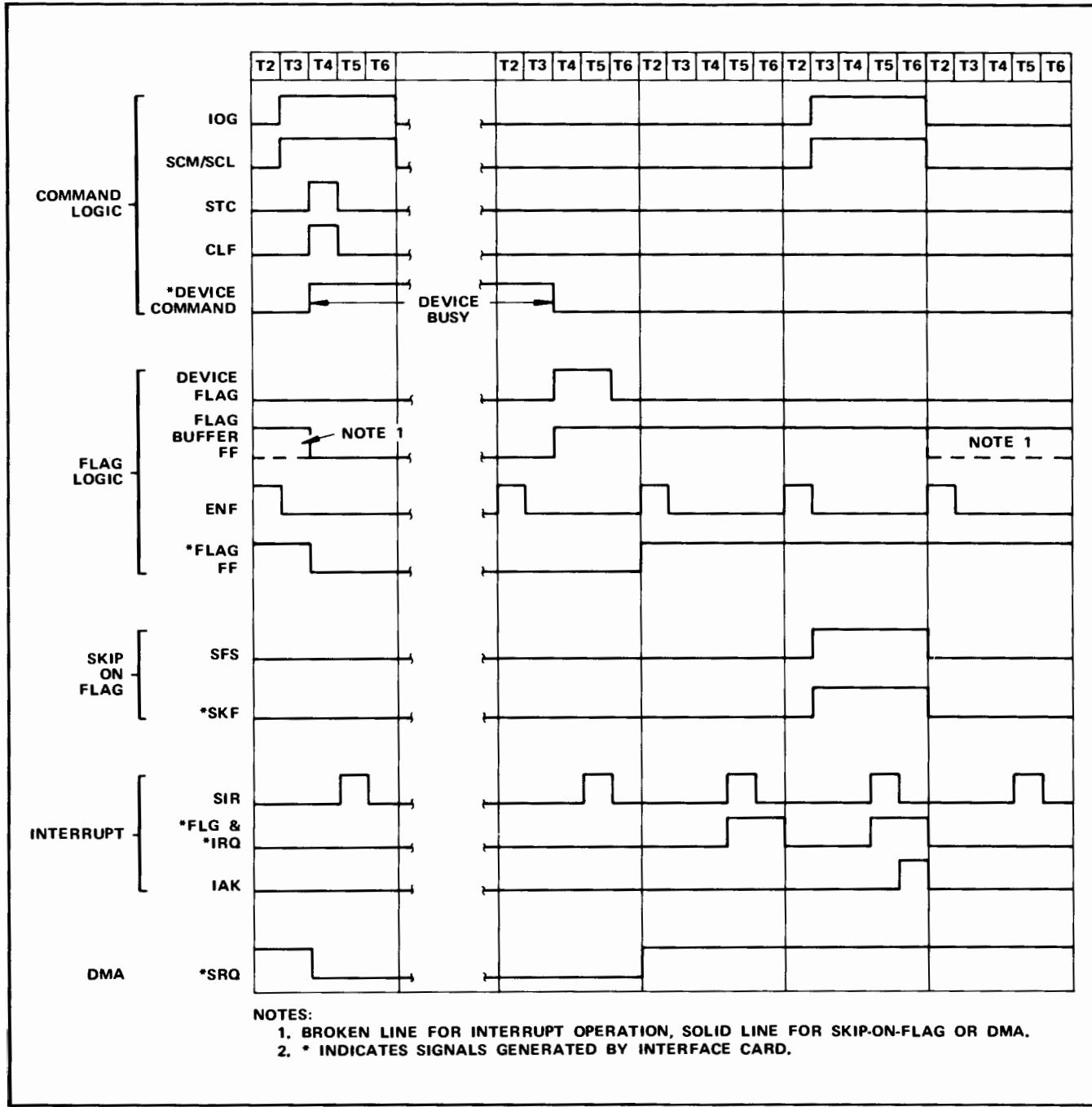


Figure 4-3. Interrupt Operation Flow Chart

Computer
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NOTES: 1. BROKEN LINE FOR INTERRUPT OPERATION, SOLID LINE FOR SKIP-ON-FLAG OR DMA
 2. * INDICATES SIGNALS GENERATED BY INTERFACE CARD

Figure 4-4. Overall Timing Diagram Showing Operation with 2114, 2115, and 2116 Computers



2118-US1

Figure 4-5. Overall Timing Diagram Showing Operation with 2100 and 21MX Computers

in one machine cycle. When the Flag FF on the interface card is set, the interface card supplies a true SRQ signal which enables the DMA circuits. The DMA circuits suspend the computer program for one machine cycle and provide the necessary signals to transfer the 8-bit word and start the tape punch.

4-35. Refer to the applicable DMA option operating and service manual for detailed information on DMA controlled I/O operations.

4-36. OUTPUT REGISTER LOGIC.

4-37. After the computer has been signaled that the tape punch is not busy, the output data word can be transferred to the interface card output storage register. This is accomplished with an OTA or OTB instruction (addressed to the tape punch interface card) in the main program or in an interrupt subroutine. Signals to the interface card resulting from an OTA or OTB instruction are SCM, SCL,

IOG, and IOO. The IOO signal latches the 8-bit data word into the output storage register.

4-38. COMMAND LOGIC.

4-39. With data in the interface card output storage register, the tape punch need only be commanded to punch the data on tape. An STC xx,C (combined Set Control and Clear Flag) instruction with the select code (xx) of the tape punch interface sets the Control and Command FFs and clears the Flag and Flag Buffer FFs. The set side of the Command FF is level-amplified and sent to the tape punch as a Punch signal.

4-40. The set side of the Control FF provides one of the enabling signals for the interrupt logic (see paragraph 4-30). Flag and Flag Buffer FFs in the clear state enable the interface card flag logic. The tape punch will now punch the 8-bit data word and return a Flag signal when it is ready for another punch operation.

SECTION V

MAINTENANCE

5-1. INTRODUCTION.

5-2. This section provides maintenance information for the tape punch interface kit. Included are preventive maintenance instructions, troubleshooting instructions, and maintenance data consisting of a signal index for the interface cable (table 5-2), information pertaining to the integrated circuit characteristics and pin connections (figure 5-1), replaceable parts list for the interface card (table 5-1), and an interface card parts location and logic diagram (figure 5-2).

5-3. PREVENTIVE MAINTENANCE.

5-4. Preventive maintenance for the tape punch interface kit should be performed along with the preventive maintenance routines for the computer system.

5-5. Preventive maintenance consists of running the diagnostic test described in the *High Speed Tape Reader/Punch Diagnostic Reference Manual*, part no. 12597-90031. Also, visually inspect the interface card, cable, and connectors for burned or broken components, connections, and insulation.

5-6. TROUBLESHOOTING.

5-7. Troubleshooting the interface card is accomplished by running the diagnostic test described in the *High Speed Tape Reader/Punch Diagnostic Reference Manual*, part no. 12597-90031 and analyzing error halts as they occur.

5-8. Use the maintenance data contained in this section to further isolate faulty components.

Table 5-1. Tape Punch Interface Card Replaceable Parts List

REFERENCE DESIGNATION	HP PART NO.	DESCRIPTION	MFR CODE	MFR PART NO.
C1 thru C8,18	0140-0198	Capacitor, Fxd, Mica, 200 pF, 5%	28480	0140-0198
C9 thru C16	0140-0191	Capacitor, Fxd, Mica, 56 pF, 5%	28480	0140-0191
C17	0140-0192	Capacitor, Fxd, Mica, 68 pF, 5%	28480	0140-0192
C19,22	0160-0153	Capacitor, Fxd, My, 1000 pF, 10%, 200 VDCW	28480	0160-0153
C20,21	0160-0154	Capacitor, Fxd, My, 2200 pF, 10%	28480	0160-0154
C23 thru C32	0180-0197	Capacitor, Fxd, Elect, 2.2 uF, 10%, 20 VDCW	56289	150D225X9020A2
CR9 thru CR17	1901-0040	Diode, Si, 30 mA, 30 WV	07263	FDG 1088
MC15,36	1820-0068	Integrated Circuit, TTL	56289	USN7410A
MC16,26,47	1820-0956	Integrated Circuit, CTL	07263	SL3459
MC17,25,27,37,46,57,86,94	1820-0054	Integrated Circuit, TTL	56289	USN7400A
MC34,44,64,74	1820-0301	Integrated Circuit, TTL	01295	SN7475N
MC35	1820-0069	Integrated Circuit, TTL	56289	USN7420A
MC45,55,65,75	1820-0974	Integrated Circuit, CTL	07263	SL4817
MC56,66	1820-0071	Integrated Circuit, TTL	56289	USN7440A
Q1 thru Q18	1854-0215	Transistor, Si, NPN	04713	SPS3611
R1 thru R8,18	0757-0417	Resistor, Fxd, Flm, 562 ohms, 1%, 1/8W	28480	0757-0417
R9 thru R17	0757-0442	Resistor, Fxd, Flm, 10.0k, 1%, 1/8W	28480	0757-0442
R19,22,23	0698-3445	Resistor, fxd, Flm, 348 ohms, 1%, 1/8W	28480	0698-3445
R20,30,31	0698-3440	Resistor, Fxd, Flm, 196 ohms, 1%, 1/8W	28480	0698-3440
R21	0698-0082	Resistor, Fxd, Flm, 464 ohms, 1%, 1/8W	28480	0698-0082
R24,25,28,32	0757-0280	Resistor, Fxd, Flm, 1k, 1%, 1/8W	28480	0757-0280
R26,27	0757-0401	Resistor, Fxd, Flm, 100 ohms, 1%, 1/8W	28480	0757-0401
R29	0757-1094	Resistor, Fxd, Flm, 1.47k, 1%, 1/8W	28480	0757-1094
R101,103,105,107,109,111,113, 115,117,118	1810-0008	Resistor Network (6 fxd flm resistors)	28480	1810-0008
R119 thru R122	1810-0020	Resistor Network (7 fxd flm resistors)	28480	1810-0020
W1 thru W7	8159-0005	Jumper Wire	28480	8159-0005

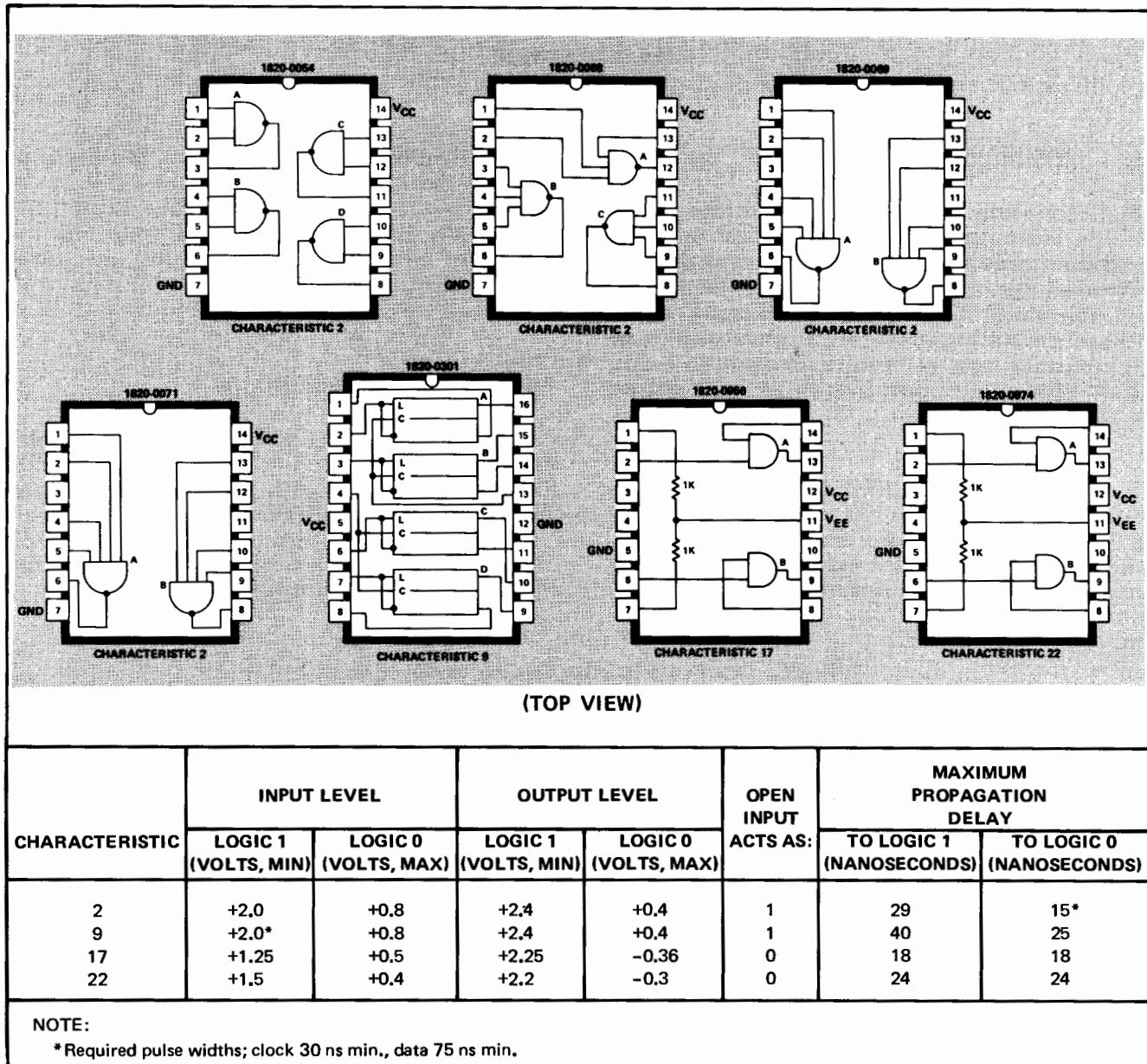


Figure 5-1. Integrated Circuit Pin Connections and Characteristics

Table 5-2. Interface Cable Signal Index

48-PIN CONNECTOR, PIN NO.	TAPE PUNCH CONNECTOR, PIN NO.	SIGNAL
A	1	Bit 1 (CH 1)
B	2	Bit 2 (CH 2)
C	3	Bit 3 (CH 3)
D	4	Bit 4 (CH 4)
E	5	Bit 5 (CH 5)
F	6	Bit 6 (CH 6)
H	7	Bit 7 (CH 7)
J	8	Bit 8 (CH 8)
AA	11	Punch (PI)
6	18	Low Tape (TL)
23	12	Flag (PR)
24, BB	25	Ground (OV)

NOTE: Pins 9 and 24, and pins 7 and 21 are jumpered in the tape punch connector of the interconnecting cable. (See figure 2-1.)

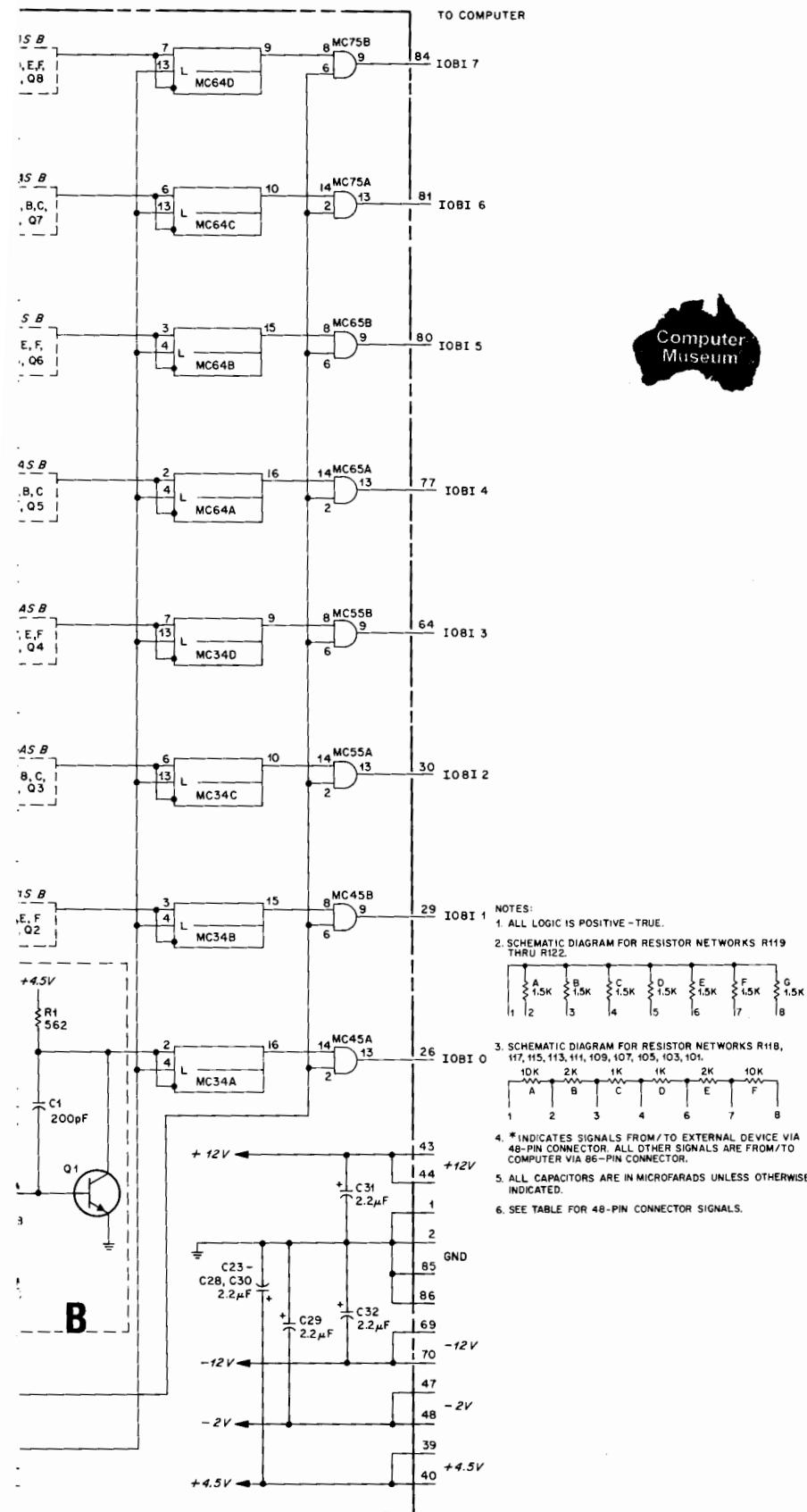
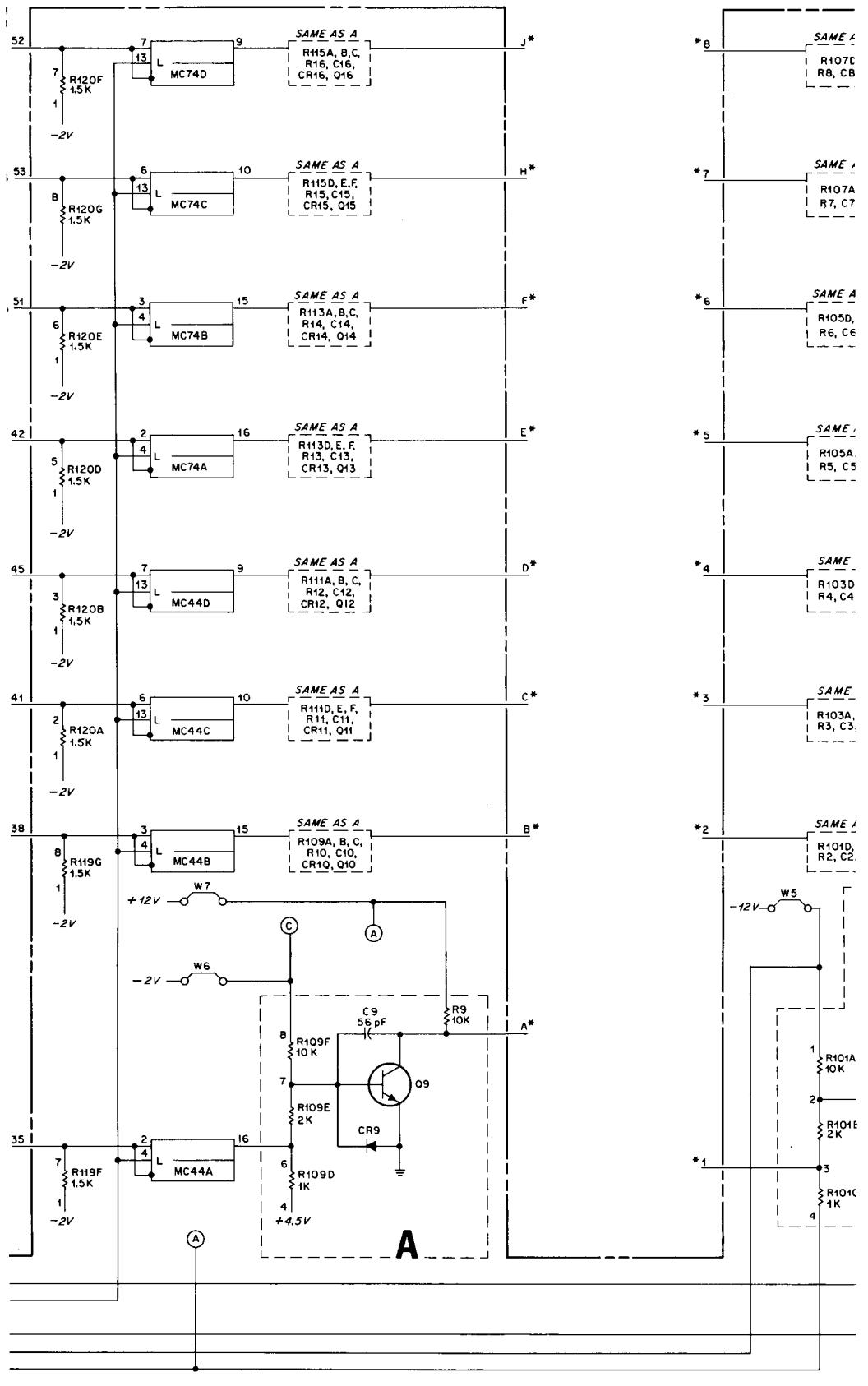
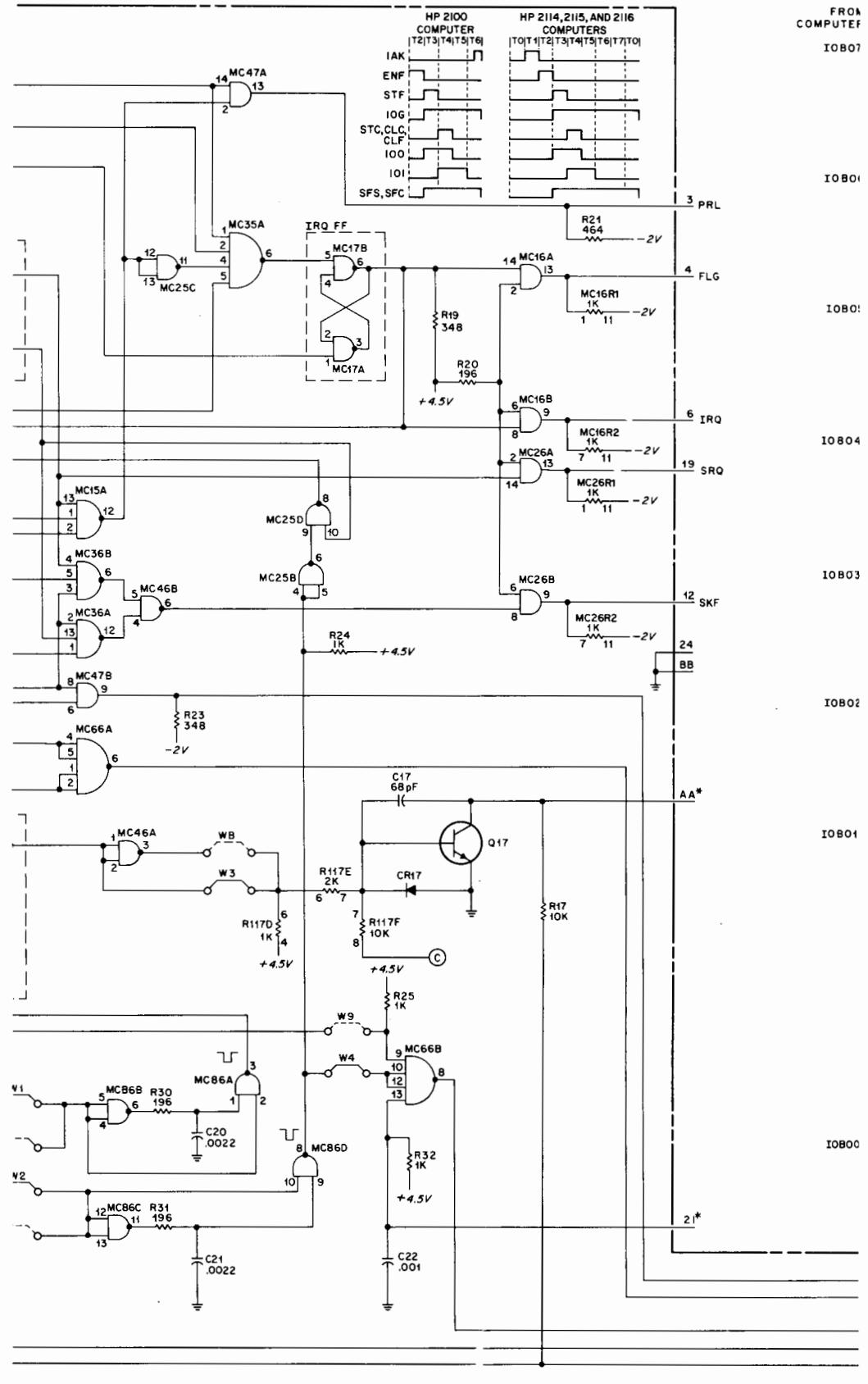
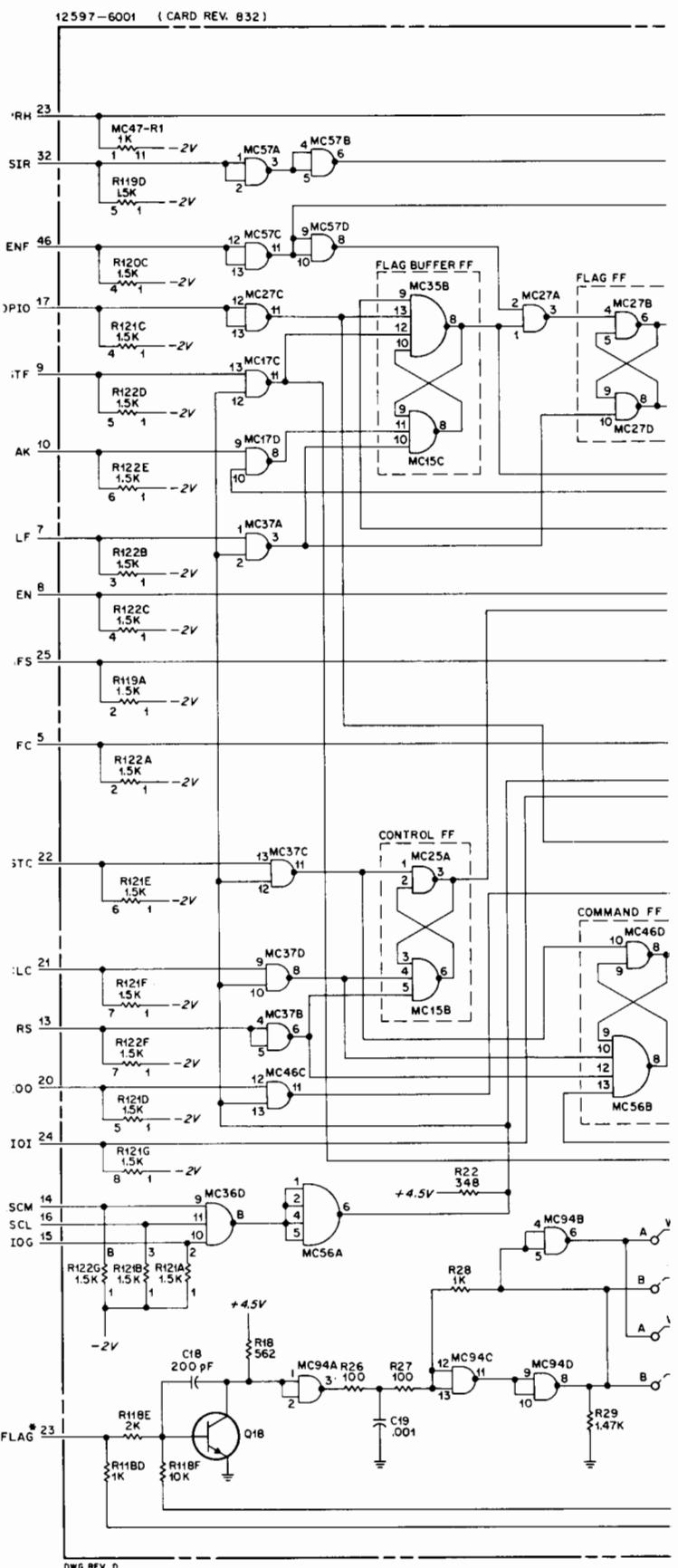


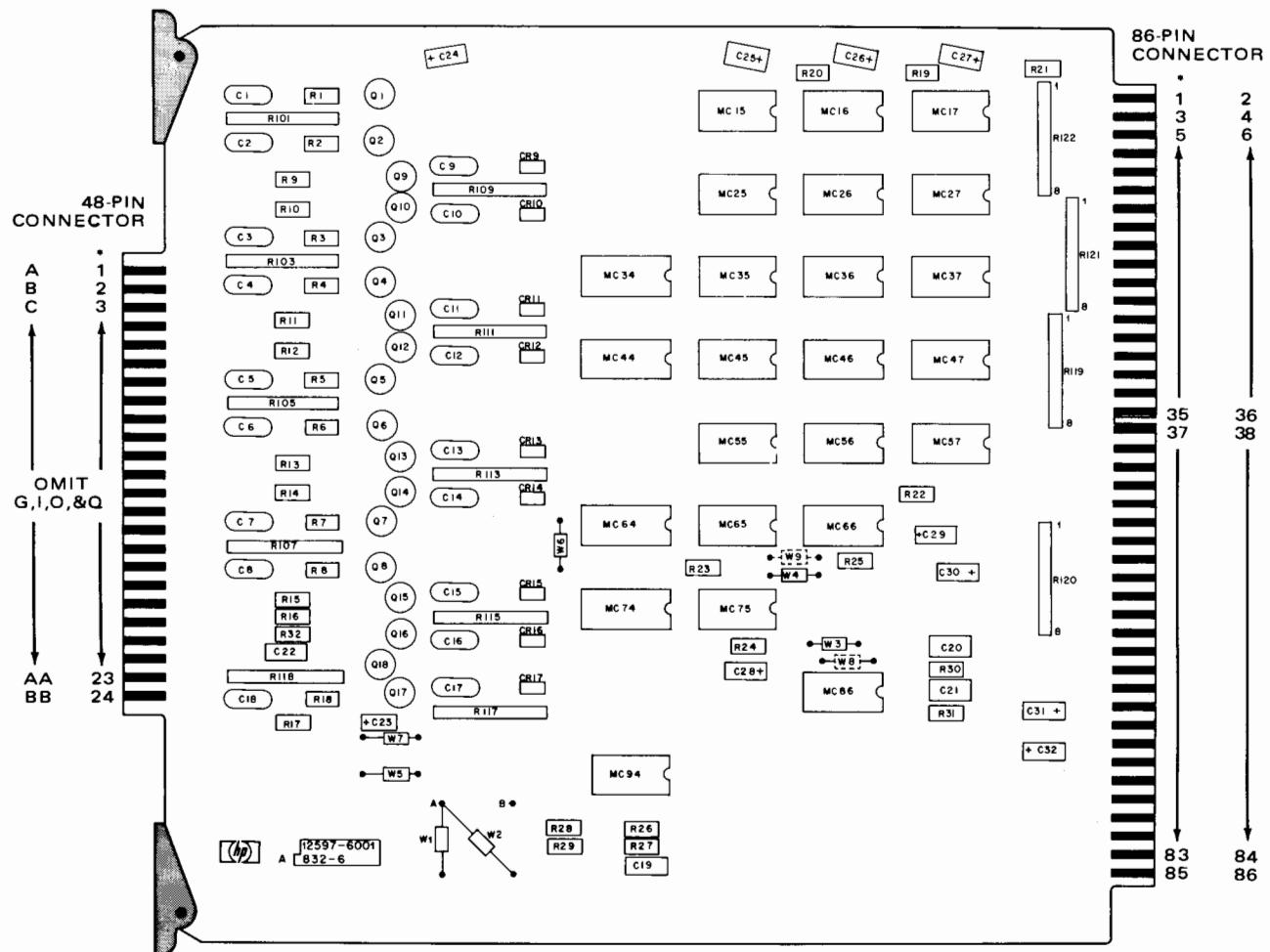
Figure 5-2. Tape Punch Interface Card Parts Location Diagram and Logic Diagram







DWG REV. D



SECTION VI

REPLACEABLE PARTS

6-1. INTRODUCTION.

6-2. This section provides information for ordering replacement parts for the 12597A-005 Tape Punch Interface Kit. Table 6-1 is a numerical listing of all replaceable parts in the interface kit.

6-3. An interface card replaceable parts list (table 5-1) and parts location diagram (figure 5-2) are provided in Section V of this manual.

6-4. Tables 5-2 and 6-1 list the following information for each replaceable part:

- a. Reference designation of the part (table 5-1 only). (Refer to table 6-2 for an explanation of the abbreviations used in the REFERENCE DESIGNATION column.)
- b. Hewlett-Packard part number.
- c. Description of the part. (Refer to table 6-2 for an explanation of the abbreviations used in the DESCRIPTION column.)

d. A five digit code that corresponds to the manufacturer of the part. (Refer to table 6-3 for a code list of manufacturers.)

e. Manufacturers part number.

f. Total quantity (TQ) of each part used in the kit or assembly (table 6-1 only).

6-5. ORDERING INFORMATION.

6-6. To order replacement parts, address the order or inquiry to the nearest Hewlett-Packard Sales and Service Office. Refer to the list at the back of this manual for addresses. Specify the following information for each part ordered:

- a. Identification of the instrument, kit or assembly containing the part (refer to paragraph 1-8).
- b. Hewlett-Packard part number for each part.
- c. Description of each part.
- d. Circuit reference designation for each part (if applicable).



Table 6-1. Numerical Listing of Replaceable Parts

HP PART NO.	DESCRIPTION	MFR CODE	MFR PART NO.	TQ
0140-0191	Capacitor, Fxd, Mica, 56 pF, 5%	28480	0140-0191	8
0140-0192	Capacitor, Fxd, Mica, 68 pF, 5%	28480	0140-0192	1
0140-0198	Capacitor, Fxd, Mica, 200 pF, 5%	28480	0140-0198	9
0160-0153	Capacitor, Fxd, My, 1000 pF, 10%, 200 VDCW	28480	0160-0153	2
0160-0154	Capacitor, Fxd, My, 2200 pF, 10%	28480	0160-0154	2
0180-0197	Capacitor, Fxd, Elect, 2.2 uF, 10%, 20 VDCW	56289	150D225X9020A2	10
0698-0082	Resistor, Fxd, Flm, 464 ohms, 1%, 1/8W	28480	0698-0082	1
0698-3440	Resistor, Fxd, Flm, 196 ohms, 1%, 1/8W	28480	0698-3440	3
0698-3445	Resistor, Fxd, Flm, 348 ohms, 1%, 1/8W	28480	0698-3445	3
0757-0280	Resistor, Fxd, Flm, 1k, 1%, 1/8W	28480	0757-0280	4
0757-0401	Resistor, Fxd, Flm, 100 ohms, 1/8W	28480	0757-0401	2
0757-0417	Resistor, Fxd, Flm, 562 ohms, 1%, 1/8W	28480	0757-0417	9
0757-0442	Resistor, Fxd, Flm, 10.0 ohms, 1%, 1/8W	28480	0757-0442	9
0757-1094	Resistor, Fxd, Flm, 1.47k, 1%, 1/8W	28480	0757-1094	1
1251-0332	Connector, PC	02660	143-024-08 (1158)	1
1810-0008	Resistor Network (6 fxd flm resistors)	28480	1810-0008	10
1810-0020	Resistor Network (7 fxd flm resistors)	28480	1810-0020	4
1820-0054	Integrated Circuit, TTL	56289	USN7400A	8
1820-0068	Integrated Circuit, TTL	56289	USN7410A	2
1820-0069	Integrated Circuit, TTL	56289	USN7420A	1
1820-0071	Integrated Circuit, TTL	56289	USN7440A	2
1820-0301	Integrated Circuit, TTL	01295	SN7475N	4
1820-0956	Integrated Circuit, CTL	07263	SL3459	3
1820-0974	Integrated Circuit, CTL	07263	SL4817	4
1854-0215	Transistor, Si, NPN	04713	SPS3611	18
1901-0040	Diode, Si, 30 mA, 30 WV	07263	FDG 1088	9
8159-0005	Jumper Wire	28480	8159-0005	7
12597-6001	Tape Punch Interface Card	28480	12597-6001	1
12597-60061	Cable	28480	12597-60061	1
12597-90025	Operating and Service Manual	28480	12597-90025	1

Table 6-2. Reference Designations and Abbreviations

REFERENCE DESIGNATIONS			
A = assembly B = motor BT = battery C = capacitor CR = diode DL = delay line DS = indicator (lamp) E = misc hardware F = fuse FL = filter J = receptacle connector	K = relay L = inductor M = meter MC = microcircuit P = plug connector Q = transistor R = resistor RT = thermistor S = switch T = transformer	TB = terminal board TP = test point U = integrated circuit V = vacuum tube, neon bulb, photocell, etc. VR = voltage regulator W = cable, jumper X = socket Y = crystal Z = tuned cavity, network	
ABBREVIATIONS			
A = amperes ac = alternating current ad = anode Al = aluminum AR = as required adj = adjust Assy = assembly	gnd = ground(ed) gra = gray grn = green	H = henries Hg = mercury hr = hour(s) Hz = hertz hdw = hardware hex = hexagon, hexagonal	ph = Phillips head pk = peak p-p = peak-to-peak pt = point PIV = peak inverse voltage PNP = positive-negative-positive PWV = peak working voltage porc = porcelain posn = position(s) pozi = pozidrive ph brz = phosphor bronze
B = base bp = bandpass bfo = beat frequency oscillator blk = black blu = blue brn = brown brs = brass Btu = British thermal unit bwc = backward wave oscillator Be Cu = beryllium copper	ID = inside diameter IF = intermediate frequency in. = inch, inches I/O = input/output int = internal incl = include(s) insul = insulation, insulated impgrg = impregnated incand = incandescent	k = kilo (10^3), kilohm lp = low pass	rf = radio frequency rdh = round head rmo = rack mount only rms = root-mean-square RWV = reverse working voltage rect = rectifier r/min = revolutions per minute
C = collector cw = clockwise ccw = counterclockwise cer = ceramic cmo = cabinet mount only com = common crt = cathode-ray tube CTL = capacitor-transistor logic cath = cathode cd pl = cadmium plate Comp = composition conn = connector compl = complete	m = milli (10^{-3}) M = mega (10^6), megohm My = Mylar mfr = manufacturer mom = momentary mtg = mounting misc = miscellaneous met ox = metal oxide mintr = miniature	n = nano (10^{-9}) nc = normally closed or no connection Ne = neon no. = number or normally open np = nickel plated NPN = negative-positive-negative NPO = negative positive zero (zero temperature coefficient) NSR = not separately replaceable NRFR = not recommended for field replacement	s = second SB = slow-blow Se = selenium Si = silicon scr = silicon-controlled rectifier sil = silver sst = stainless steel stl = steel spcl = special spdt = single-pole, double-throw spst = single-pole, single-throw semicond = semiconductor
dc = direct current dr = drive DTL = diode-transistor logic dep = deposited carbon dpdt = double-pole, double-throw dpst = double-pole, single-throw	OD = outside diameter OBD = order by description orn = orange ovh = oval head oxd = oxide	Ta = tantalum td = time delay Ti = titanium tgl = toggle thd = thread tol = tolerance TTL = transistor-transistor logic term = terminal	U (μ) = micro (10^{-6})
E = emitter ext = external encap = encapsulated elctlt = electrolytic	p = pico (10^{-12}) PC = printed circuit	V = volt(s) var = variable vio = violet VDCW = direct current working volts	V = watts ww = wirewound wht = white WIV = working inverse voltage yel = yellow
F = farads FF = flip-flop fh = flat head flm = film fxd = fixed filh = fillister head			
G = giga (10^9) Ge = germanium gl = glass			

Table 6-3. Code List of Manufacturers

The following code numbers are from the Federal Supply for Manufacturers Cataloging Handbooks H4-1 and H4-2, and the latest supplements.					
CODE NO.	MANUFACTURER	ADDRESS	CODE NO.		
01295	Texas Instruments, Inc., Transistor Products Div.	Dallas, Texas	07263	Fairchild Camera & Instr. Corp., Semiconductor Div.	Mountain View, Cal.
02660	Amphenol-Borg Electronics Corp.	Broadview, Ill.	28480	Hewlett-Packard Co.	Palo Alto, Cal.
04713	Motorola, Inc., Semiconductor Prod. Div. .	Phoenix, Ariz.	56289	Sprague Electric Co.	North Adams, Mass.



MANUAL PART NO. 12597-90025
MICROFICHE PART NO. 12597-90029

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